

ELECTRONICALLY FILED ON MAY 3, 2007

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of inventor(s):

Marco Karnezos

Application No. 10/632,552

Confirmation No. 2572

Filing Date: 02 August 2003

Title: Semiconductor multi-package module
having package stacked over die-up
flip chip ball grid array package and
having wire bond interconnect
between stacked packages

Group Art Unit: 2815

Examiner: Chris C. Chu

CUSTOMER NO. 22470

Attention: Office of Petitions

MAIL STOP PETITION

Commissioner for Patents

P.O. Box 1450


Alexandria, VA 22313-1450

PETITION FOR EXTENSION OF TIME

Dear Sir:

Applicant requests a five-month extension of time in the above-identified U.S. patent application. The appropriate fee ((\$2,160) is being electronically submitted herewith. Applicant is separately submitting a continuation application in lieu of an appeal brief.

Fee Authorization. The Commissioner is hereby authorized to charge any additional fee(s) determined to be due in connection with this communication, or credit any overpayment, to our Deposit Account No. 50-0869 (CPAC 1017-5.1).

Respectfully submitted,
 *Reg. No. 33,407*

Bill Kennedy, Reg. No. 33,407

Dated: 03 May 2007

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